



IBIS Open Forum Minutes

Meeting Date: **December 5, 2014**

Meeting Location: **Teleconference**

VOTING MEMBERS AND 2014 PARTICIPANTS

Altera	David Banas, Kundan Chand, Hsinho Wu
ANSYS	Lan Chen, Minggang Hou, Jianbo Liu, Peng Wang Shulong Wu, Guoli Yin, Jizhi Zhao, Tommy Chien Elly Dong, Milkman Hsuan, Winny Huang Stanley Hangwei Kuo, James Wang Jean Yacchin Wang, Jerry Wang, Benson Peishen Wei Jack Wu, Tinghao Yeh, Tohru Watanabe, Shigeru Sano Curtis Clark*
Applied Simulation Technology	Fred Balistreri, Norio Matsui
Cadence Design Systems	Ambrish Varma, Brad Brim*, Joy Li, Kumar Keshavan Ken Willis, Yingxin Sun, Joshua Luo, John Phillips Aileen Chen, Lanbing Chen, Zhiyu Guo, Jinsong Hu Rachel Li, Lavia Liu, Ping Liu, Yubao Meng Feng Miao, Zuli Qin, Haisan Wang, Hui Wang Yitong Wen, Clark Wu, Benny Yan Rong Zhang, Wenjian Zhang, Alex Zhao Zhangmin Zhong, Kent Ho, Thunder Lay, Skipper Liang Paddy Wu, Candy Yu, Ian Yu, Ikuo Masuko Morihiro Nakazato
Ericsson	Anders Ekholm, Zilwan Mahmod, Feng Shi Wenyan Xei
Huawei Technologies	Jinjun Li, Xiaoqing Dong, Zanglin Yuan, Han Li Haiping Cao, Yu Chen, Peng Huang, Hongxing Jiang Xueping Jiao, Aojie Li, Xusheng Liu, Zipeng Luo Longfang Lv, Luya Ma, Xiao Peng, Wenju Sheng Jianhua Wang, Shengli Wang, Huichao Weng Zhengrong Xu, Gezi Zhang, Zhenyi Zhu
Infineon Technologies AG	(Christian Sporrer)
Intel Corporation	Michael Mirmak*, Jon Powell, Riaz Naseer Udy Shrivastava, Mustafa Yousuf, Jimmy Jackson Pietro Brenner, Todd Bermensolo, Denis Chen Jimmy Hsu, Cucumber Lin, Jeff Loyer, Thomas Su
IO Methodology	Lance Wang*, Michelle Coombs
Keysight Technologies (Agilent)	Radek Biernacki*, Nilesh Kamdar, Colin Warwick Graham Riley, Pegah Alavi, Fangyi Rao Heidi Barnes, Dimitrios Drogoudis, Tao Zhang Xianzhao Zhao
LSI (Avago)	Xingdong Dai, Min Huang, Anaam Ansari, Brian Burdick Venkatesh Avula

Maxim Integrated Products	Hassan Rafat
Mentor Graphics	Arpad Muranyi*, John Angulo, Fadi Deek, Chuck Ferry Thomas Groebli, Larry Shi, Kenji Kushima Kazuhiro Kadota
Micron Technology	Randy Wolff*
Micron Akita	Katsunobu Noguchi
Micron Memory Japan	Fumiyuki Osanai, Hiromasa Takeda
Qualcomm	Jaimeen Shah, Srinivasa Rao, Senthil Nagarathinam
Signal Integrity Software	Mike LaBonte*, Walter Katz*, Todd Westerhoff, Michael Steinberger
Synopsys	Ted Mido*, Scott Wedge, Kevin Cameron, Rita Horner Xuefeng Chen, Jinghua Huang, Lianpeng Sang Deng Shi
Teraspeed Labs	Bob Ross*, Tom Dagostino, Scott McMorrow
(Teraspeed Consulting Group)	
Toshiba	Hiroyuki Ikegami, Toshihiro Tsujimura, Hideo Oie* Masato Kanie, Atsushi Tomishima Yasuki Torigoshi
Toshiba Information Systems	Yasuyuki Inaba, Mari Kuroki
Toshiba Microelectronics	Jyunya Masumi
Toshiba Semiconductor & Storage	Toru Amamoto, Yoshinori Fukuba, Shinya Harada Yasunobu Umemoto
Xilinx	Ravindra Gali
ZTE Corporation	Fengling Gao, Lili Wei, Zhongmin Wei Changgang Yin, Shunlin Zhu
Zuken	Michael Schaefer, Amir Wallrabenstein, Griff Derryberry Reinhard Remmert, Kiyohisa Hasegawa

OTHER PARTICIPANTS IN 2014

3M	Shiang Yao
Advanet	Kohji Tomita
Advantest Corporation	Yasutaka Aoki
ADVLSI	Pierre Dermay, Juanna Gao
AET	Chihiro Ueda
Alcatel-Lucent	Yishan Li
AMD	Tadashi Arai
Amlogic	Jiaxing Ye, Weiguo Zhu
Apollo Giken Co.	Naoya Iisaka, Satoshi Endo
Avant Technology	Jiaying Sun, Jyam Huang, Chloe Yang
Azuma Co.	Teruaki Hirose
Canon	Yuji Ishikawa, Kenta Koshida, Syoji Matsumoto Takeshi Nagata
Carleton University	Ramachandra Achar
Casio Computer	Yasuhisa Hayashi, Ikuo Imada

Celestica	Lei Liu, Xu Yan
Chinese Academy of Engineering Physics (CAEP), Institute of Electronic Engineering (5th Institute)	Anju Tan, Liang Yin
Cisco Systems	Hongxian Yin
Continental Automotive	Catalin Negrea
CST	Stefan Paret
Cybernet Systems	Shinobu Koakutsu
Design Methodology Lab	Motoh Tanaka
ECL Advantage	Thomas Iddings
EMC Corporation	Sherman Chen
Flatoak Co.	Hiroshi Sakai
Freescale Semiconductor	Asher Berkovitz, Takahiro Sato
Fujitsu Advanced Technologies	Shogo Fujimori, Kazuhiro Kanai, Kumiko Teramae Hidenobu Shiihara
Fujitsu Interconnect Technologies	Syunsuke Fujisawa
Fujitsu Laboratories	Toshiki Iwai
Fujitsu Limited	Kohichi Yoshimi
Fujitsu Microelectronics Solutions	Yutaka Ide
Fujitsu Semiconductor	Jyunko Nakamoto, Yu Kamata, Fumiyo Kawafuji
Fujitsu VLSI	Hiroki Kubota, Yuji Nakagawa, Hajime Ohmi
Fuji Xerox Advanced Technology	Ryota Seki, Satoshi Kodama
Fuji Xerox Manufacturing	Rumi Maeda
Fuzhou Rockchip Electronics	Xinjun Wang
Gigabyte Technology	Eric Chien, Mountain Lin, Alex Lu
Giga Hertz Technology	Chisato Kawamura
H3C	Xinyi Hu, Xiaoqun Li
Hamamatsu Photonics K.K.	Akahi Inoguchi
Hangzhou Hikvision Digital Technology	Wenquan Hu, Jia Zhang
Hewlett Packard	Ting Zhu
Himax Technologies	Brian Kuo, Ren-Yu Wang, Josh Wu
Hisense Group	Golden Qian
Hitachi Information & Communication Engineering	Yoshifumi Takada
Hitachi ULSI Systems Co.	Hiroshi Uematsu, Sadahiro Nonoyama
Hoei Co.	Tatsuya Chiba
Hong Kong University	Lijun Jiang
Hon-Hai Precision (Foxconn)	Ryan Lung-Yu Hou, Daniel Ying-Tso Lai Chris Chia-Nan Pai
IBM	Adge Hawes
ILI Technology Corp.	Chia-Cheng Wu
Innotech Corporation	Sinobu Seki
Instituto de Telecomunicações	Wael Dghais
Japan Radio Co.	Hiroto Katakura

JEITA	Yousuke Kanamaru, Ryosuke Miyagawa Akahito Nagamoto, Kyouji Yamazaki
JONHON	Guoqi Zhou
JVC Kenwood Corporation	Hidetoshi Suzuki
KEI Systems	Shinichi Maeda
KSK Co.	Yutaka Shishido
Lapis Semiconductor	Katsuhiro Hisaka
Lattice Semiconductor	Xu Jiang
Lenovo	John Lin, Alan Sun
LUXSHARE-ICT	Jet Shen, Chenhui Zeng
Macronix Microelectronics	Donghe Tang
Marvell	Weizhe Li, Xike Liu, Fang Lv, Banglong Qian Yuyang Wang, Liang Wu
MD Systems	Hidetoshi Ogawa
Mediatek	Alice Lin, Delbert Liao
Megachips Corp.	Kenichiro Kobayashi
Mellanok Technologies	Piers Dawe
Microsemi	Nizar Abdallah, Ann Lau
Modech	Yasuo Kawahara, Masanori Shimasue, Minoru Tanaka
Montage Technology	Xiaoliang Xu
Murata Manufacturing	Satoshi Arai, Naoki Iida, Kingo Kurotani
Nanium	Abel Janeiro
Nanya Technology Corp.	Chi-Wei Chen, Aiden Hsu, Tingshuo Hsu, Andre Huang Raphael Huang, Tian-De Huang, Zuo Xin
NEC Corp.	Yasuyuki Chiba
NEC Engineering	Masahiko Kuroda
Nikon Corporation	Kazuomi Tominaga, Manabu Matsumoto
Olympus Corp.	Kazuhiro Sakamoto
Oracle	Stephan Mueller
Panasonic Semiconductor Solutions Co.	Daisuke Matsuoka, Masaya Sumita
Pangya	Edgar Aguirre
Pegatron Corp.	Lance Chang, Stanley Chu, Gavin Lin
Pioneer Corp.	Kenji Sakamoto
Pioneer Micro Technology Corp.	Minoru Nakahara
Private	Seijyu Ichijyo
Proficient Design	Kishor Patel
Renesas Electronics	Genichi Tanaka, Masayasu Koumyo, Ryuichi Oikawa Kenzo Tan, Hiroyuki Uchida
Renesas System Design Corp.	Kazunori Yamada
Ricoh Company	Yasuhiro Akita, Kazumasa Aoki, Masahiko Banno Miyoko Goto, Takefumi Takizawa
Rockchip	Jiayi Song
Rohm Co.	Noboru Takizawa
SAE International	Chris Denham

Sanei Hytechs Co.	Hiroyuki Kai
Seiko Instruments	Masaya Murata
Shimadzu Corp.	Kazuo Nakajima
Sony LSI Design	Satoshi Tago
Success International Corporation	Tatsuo Futai
Sunplus Technology	Forest Hsu, Yi-Tzeng Lin
Tabula	Ben Zhou
Technische Universität Hamburg	Torsten Reuschel
Teledyne LeCroy	Larry Cao, Derek Hu, Joyce Yin
Towa Electronics	Yoshikazu Suzuki
University of Illinois	José Schutt-Ainé
VIA	Terence Hsieh, Justin Hsu
Via CPU	Leon Liang
Vitesse	Siris Tsang
Wadow	Kazuhiko Kusunoki
Winbond Electronics	Albert Lee
Wiwynn Corp.	Scott CH Lee, Kevin TK Wang
Xpeedic Technology	Wenliang Dia, Feng Ling, Zhouxiang Su
Yamanashi Avionics Co.	Yasunori Yamashita
Zhejiang Uniview Technologies	Fei Ye, Feng Ye

In the list above, attendees at the meeting are indicated by *. Principal members or other active members who have not attended are in parentheses. Participants who no longer are in the organization are in square brackets.

UPCOMING MEETINGS

The bridge numbers for future IBIS teleconferences are as follows:

Date	Meeting Number	Meeting Password
January 9, 2015	205 475 958	IBIS

For teleconference dial-in information, use the password at the following website:

<https://ciscosales.webex.com/ciscosales/j.php?J=205475958>

All teleconference meetings are 8:00 a.m. to 9:55 a.m. US Pacific Time. Meeting agendas are typically distributed seven days before each Open Forum. Minutes are typically distributed within seven days of the corresponding meeting. When calling into the meeting, follow the prompts to enter the meeting ID. For new, local international dial-in numbers, please reference the bridge numbers provided by Cisco Systems at the following link:

http://www.cisco.com/web/about/doing_business/conferencing/index.html

NOTE: "AR" = Action Required.

INTRODUCTIONS AND MEETING QUORUM

Michael Mirmak declared that a quorum was reached and the meeting could begin.

Curtis Clark introduced himself. He works on SI products and support for traditional IBIS and AMI models at ANSYS. He has attended IBIS ATM task group meetings for several years and has worked on BIRDS and BUGs.

CALL FOR PATENTS

Michael Mirmak called for any patents or pending patents related to the IBIS 3.2, IBIS 4.2, IBIS 5.1, IBIS 6.0, Touchstone 2.0, IBIS-ISS 1.0 or ICM 1.1 specifications. No patents were declared.

REVIEW OF MINUTES AND ARS

Randy Wolff called for comments regarding the minutes of the October 24, 2014 IBIS Open Forum teleconference. The minutes were approved without changes. He then called for comments regarding the minutes of the November 14, 2014 Asian IBIS Summit in Shanghai. The minutes were approved without changes. He then called for comments regarding the minutes of the November 17, 2014 Asian IBIS Summit in Taipei. The minutes were approved without changes.

ANNOUNCEMENTS

None.

CALL FOR ADDITIONAL AGENDA ITEMS

Bob Ross requested time to discuss social media.

MEMBERSHIP STATUS AND TREASURER'S REPORT

Bob Ross reported no change in membership with 22 paid members. The treasury sits at \$41,185. The growth is due to Asian Summit expenses for China being paid from the account Lance Wang holds instead of from SAE. \$21,600 is the accumulation of dues, \$5,400 is from parser sales and \$14,185 is from Summit accumulation. We are still waiting on the Taipei Summit hotel balance from Michael Mirmak. Bob is also working on parser license issues holding up some potential parser payments. He noted that he does not know how we settle with SAE for any yearly dues. Michael asked if SAE is expecting the same payment required from TechAmerica. Bob responded that Chris Denham of SAE has not given a specific assessment.

WEB PAGE AND MAILING LIST ADMINISTRATION

Mike LaBonte reported that he has a standing item to investigate what platform we might

migrate our web pages to. He has had some conversations with SAE. We actually have a web page at SAE, but it only offers a few basic things such as the ability to upload documents. We will have to look elsewhere for a more professional website platform.

Some people in Asia at the Summits commented that they would like more use of social media for IBIS. Michael Mirmak said that the assumption that email and the web as the primary source for IBIS announcements and discussions are not enough. Using social media for events announcements and real time discussion of issues was thought to be better. Michael noted that we'd need to support several social media platforms to be effective worldwide. Mike has looked into services such as LinkedIn, Sina Weibo, Twitter, WhatsApp and others. Our current emails would need to be posted as web pages with links posted to social media. Lance Wang reported that he heard in Asia that a lot of engineers use mobile platforms and use social media for announcements. Email in China, even from freelists usually goes into junk folders in company email filters. Social media could be used a lot for meeting announcements, BIRDs, officer voting, etc. This could be more effective for Asia. Which social media platform to pick is another discussion.

Mike reported that a yahoo-based email sent to the IBIS list did not go to about 10% of the list recipients. Mike has looked into freelists services for our IBIS emails. Our task groups already use freelists. Also, freelists allows messages to get manually cross-posted to social media sites.

LIBRARY UPDATE

No update.

INTERNATIONAL/EXTERNAL ACTIVITIES

- Conferences

Michael Mirmak mentioned the China Semiconductor Industry Association ICCAD conference in Hong Kong December 11-12. The EDA Center of the Chinese Academy of Sciences is involved in the conference and has a lot of EDA and IBIS info on its website. More information is available at:

<http://www.cicmag.com/bbx/856303-856303.html>

<http://www.eda.ac.cn/>

- Press Update

None.

ORGANIZATIONAL ACTIVITIES

Bob Ross noted we need to decide on our dues for next year. Bob moved to keep the dues at \$900 for 2015. This is for membership only and does not include a parser license. Radek Biernacki seconded the motion. There were no objections.

Michael Mirmak noted that our current charter goes back about 20 years. There has been work

by the board to turn the charter into an updated policies and procedures document. A major change is to allow online voting for officers' elections. Some details are still being worked out. A vote to change the charter will be difficult to hold since it requires significant member company participation, but it should happen early next year. Bob requested that the officers meet soon to finalize the proposed charter changes.

SUMMIT PLANNING AND STATUS

- Asian IBIS Summit Reports

Michael Mirmak thanked Lance Wang, Bob Ross and Anders Ekholm for their help organizing and running the events. Bob noted that the Shanghai Summit had 11 presentations and 98 people, the Taipei Summit had 8 presentations and 59 attendees, and the Yokohama Summit had 9 presentations and 111 people attending. Bob thanked the sponsors again. Lance commented that Yokohama was only a half day Summit but had 9 presentations. Lance added that Lanbing Chen noted at the Shanghai Summit that we have a vendor neutral presentations requirement, but Lanbing asked if we could allow presentations of test cases that had more vendor-specific content. This would be more like DesignCon. Bob noted that this could be useful for attendees, but we need to see if it is allowed by SAE rules. He had concerns about vendors becoming too competitive with their presentations. Michael asked Bob to take an AR to see what is allowed by SAE rules. Arpad Muranyi wondered if this could lead to inclusion of vendor-specific language in the IBIS specification, such as HSPICE compatibility in the [External Model]. Michael asked if there were any discussions in the ATM task group about a BSS element. Arpad noted that this hasn't been discussed in awhile. Michael asked Lance to take an AR to find out about preferences for including vendor material such as having breakout sessions or a second day of a Summit to cover vendor specific material.

- DesignCon Planning

Michael reported that an IBIS Summit is tentatively scheduled for Friday, January 30, 2015. Co-location with DesignCon is not currently finalized. Arpad asked if Monday could be a possibility, since late Friday travel is difficult for East Coast attendees. Michael responded that DesignCon would not be running on Monday. Tuesday would conflict with tutorials. Bob moved to schedule the Summit for Friday, January 30, 2015. Brad Brim seconded the motion. There were no objections.

- DAC Summit and Poll

Bob noted there was a question of whether or not to hold a Summit at DAC. He sent out a poll. It had limited response but showed there was little interest in a Summit at DAC. DAC located in San Francisco is also not convenient for the San Jose community. Bob moved to not hold a Summit at DAC in 2015. Mike LaBonte seconded the motion. There were no objections.

- EPEPS Summit

Bob sent out a poll in the last week to see if there was any interest in holding a Summit at EPEPS in 2015. He noted that several IBIS participants attended EPEPS in 2014. IBIS was specifically invited to attend and hold a Summit in 2015. Lance Wang noted that the date at the end of October is too close to the Asian IBIS Summits, so that might limit attendance from those traveling to Asia.

Sponsorship opportunities for all upcoming IBIS summits are available, with sponsors receiving free mentions in the minutes, agenda, and other announcements. Contact the IBIS Board for

further details.

QUALITY TASK GROUP

Mike LaBonte reported that the group is meeting on Tuesdays at 8:00 a.m. PT. They are continuing to look at IBISCHK issues. Work on documenting the IBISCHK6 messages continues.

The work in progress can be reviewed at:

http://www.eda.org/ibis/ibischk6/ibischk_6.0.0_UserGuide_wip1.pdf

The Quality Task Group checklist and other documentation can be found at:

http://www.eda.org/ibis/quality_wip/

ADVANCED TECHNOLOGY MODELING TASK GROUP

Arpad Muranyi reported that the group is meeting regularly on Tuesdays at 12:00 p.m. PT. The last meeting for this year is on December 9. Enhancement to the C_comp model is the main discussion topic. Next Tuesday the group will resume discussion of backchannel modeling with a presentation from SiSoft on industry needs.

Task group material can be found at:

http://www.eda.org/ibis/macromodel_wip/

INTERCONNECT TASK GROUP

Michael Mirmak reported that the group is also discussing C_comp enhanced modeling and looking at boundaries of buffers, on-die interconnect and packages. The group is meeting regularly on Wednesdays at 8:00 a.m. PT.

Task group material can be found at:

http://www.eda.org/ibis/interconnect_wip/

NEW ADMINISTRATIVE ISSUES

None.

BIRD174: QUOTE CHARACTER CLARIFICATIONS

Arpad Muranyi introduced the BIRD. It is a clarification of the use of quote characters in IBIS. This BIRD clearly states that only the baseline ASCII character set is allowed, so this will specifically prohibit certain double quote characters. Radek Biernacki thought that the parser checked for this already, so this clarification would follow the parser. Radek noted that the

Editorial task group will need to make sure all examples in the specification are consistent with this BIRD requirement. Bob Ross responded to a question Arpad posed in the BIRD that, yes, file extensions are fixed in IBIS. He noted that file extensions are mentioned specifically in the BIRD, so that list may need to be updated in the future. Radek noted that the sentence could be changed to not include a specific list of IBIS file types to be more generic. Arpad thought that taking the list out from this part of the text may not help much in terms of not having to update the list when new file types are added, since it would have to be defined at least once somewhere in the specification.

Bob moved to schedule a vote on a modified BID174.1 at the next IBIS Open Forum meeting. Radek Biernacki seconded the motion. There were no objections.

Ted Mido noted that use of the back-quote ` character is troublesome and suggested that Arpad check for use of this.

BIRD125.1: MAKE IBIS-ISS AVAILABLE FOR IBIS PACKAGE MODELING

Discussion was tabled.

BIRD128.2: ALLOW AMI_PARAMETERS_OUT TO PASS AMI_PARAMETERS_IN DATA ON CALLS TO AMI_GETWAVE

Discussion was tabled.

BIRD145.3: CASCADING IBIS I/O BUFFERS WITH [EXTERNAL CIRCUIT]S USING THE [MODEL CALL] KEYWORD

Discussion was tabled.

BIRD147: BACK-CHANNEL SUPPORT

Discussion was tabled.

BIRD157: PARAMETERIZE [DRIVER SCHEDULE]

Discussion was tabled.

BIRD158.3: AMI TOUCHSTONE ANALOG BUFFER MODELS

Discussion was tabled.

BIRD161.1: SUPPORTING INCOMPLETE AND BUFFER-ONLY [COMPONENT] DESCRIPTIONS

Discussion was tabled.

BIRD163: INSTANTIATING AND CONNECTING [EXTERNAL CIRCUIT] PACKAGE MODELS WITH [CIRCUIT CALL]

Discussion was tabled.

BIRD164: ALLOWING PACKAGE MODELS TO BE DEFINED IN [EXTERNAL CIRCUIT]

Discussion was tabled.

BIRD165: PARAMETER PASSING IMPROVEMENTS FOR [EXTERNAL CIRCUIT]S

Discussion was tabled.

BIRD166: RESOLVING PROBLEMS WITH REDRIVER INIT FLOW

Discussion was tabled.

IBISCHK6 PARSER AND BUG STATUS

Bob Ross reported that IBISCHK 6.0.1 was released and the executables are available on the IBIS website. BUG155 was not fixed in this release although the fix was requested.

NEW TECHNICAL ISSUES

None.

NEXT MEETING

The next IBIS Open Forum teleconference meeting will be held January 9, 2015. The DesignCon IBIS Summit will be held January 30, 2015. No teleconferences will be available for the Summit meeting. The following IBIS Open Forum teleconference meeting will be held February 6, 2015.

Mike LaBonte moved to adjourn. Brad Brim seconded the motion. There were no objections.

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NOTES

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This meeting was conducted in accordance with ANSI guidance.

The following e-mail addresses are used:

majordomo@eda.org

In the body, for the IBIS Open Forum Reflector:
subscribe ibis <your e-mail address>

In the body, for the IBIS Users' Group Reflector:
subscribe ibis-users <your e-mail address>

Help and other commands:
help

ibis-request@eda.org

To join, change, or drop from either or both:
IBIS Open Forum Reflector (ibis@eda.org)
IBIS Users' Group Reflector (ibis-users@eda.org)
State your request.

ibis-info@eda.org

To obtain general information about IBIS, to ask specific questions for individual response, and to inquire about joining the IBIS Open Forum as a full Member.

ibis@eda.org

To send a message to the general IBIS Open Forum Reflector. This is used mostly for IBIS Standardization business and future IBIS technical enhancements. Job posting information is not permitted.

ibis-users@eda.org

To send a message to the IBIS Users' Group Reflector. This is used mostly for IBIS clarification, current modeling issues, and general user concerns. Job posting information is not permitted.

ibis-bug@eda.org

To report ibischk parser BUGs as well as tschk2 parser BUGs. The BUG Report Form for ibischk resides along with reported BUGs at:

<http://www.eda.org/ibis/bugs/ibischk/>
<http://www.eda.org/ibis/bugs/ibischk/bugform.txt>

The BUG Report Form for tschk2 resides along with reported BUGs at:

http://www.eda.org/ibis/tschk_bugs/
http://www.eda.org/ibis/tschk_bugs/bugform.txt

icm-bug@eda.org

To report icmchk1 parser BUGs. The BUG Report Form resides along with reported BUGs at:

http://www.eda.org/ibis/icm_bugs/
http://www.eda.org/ibis/icm_bugs/icm_bugform.txt

To report s2ibis, s2ibis2 and s2iplt bugs, use the Bug Report Forms which reside at:

<http://www.eda.org/ibis/bugs/s2ibis/bugs2i.txt>
<http://www.eda.org/ibis/bugs/s2ibis2/bugs2i2.txt>
<http://www.eda.org/ibis/bugs/s2iplt/bugspl.txt>

Information on IBIS technical contents, IBIS participants and actual IBIS models are available on the IBIS Home page:

<http://www.eda.org/ibis>

Check the IBIS file directory on eda.org for more information on previous discussions and results:

<http://www.eda.org/ibis/directory.html>

Other trademarks, brands and names are the property of their respective owners.

IBIS – SAE STANDARDS BALLOT VOTING STATUS

Organization	Interest Category	Standards Ballot Voting Status	November 14, 2014	November 17, 2014	November 20, 2014	December 5, 2014
Altera	Producer	Inactive	-	-	-	-
ANSYS	User	Active	X	X	X	X
Applied Simulation Technology	User	Inactive	-	-	-	-
Cadence Design Systems	User	Active	X	X	X	X
Ericsson	Producer	Active	X	X	X	-
Huawei Technologies	Producer	Inactive	X	-	-	-
Infineon Technologies AG	Producer	Inactive	-	-	-	-
Intel Corp.	Producer	Inactive	-	X	-	X
IO Methodology	User	Active	-	X	X	X
Keysight Technologies (Agilent)	User	Inactive	X	-	-	X
LSI (Avago)	Producer	Inactive	-	-	-	-
Maxim Integrated Products	Producer	Inactive	-	-	-	-
Mentor Graphics	User	Active	X	-	X	X
Micron Technology	Producer	Active	-	-	X	X
Qualcomm	Producer	Inactive	-	-	-	-
Signal Integrity Software	User	Inactive	-	-	-	X
Synopsys	User	Inactive	X	-	-	X
Teraspeed Labs	General Interest	Inactive	-	-	-	X
Toshiba	Producer	Active	-	-	X	X
Xilinx	Producer	Inactive	-	-	-	-
ZTE	User	Inactive	X	-	-	-
Zuken	User	Inactive	-	-	X	-

I/O Buffer Information Specification Committee (IBIS)

CRITERIA FOR MEMBER IN GOOD STANDING:

- MUST ATTEND TWO CONSECUTIVE MEETINGS TO ESTABLISH VOTING MEMBERSHIP
- MEMBERSHIP DUES CURRENT
- MUST NOT MISS TWO CONSECUTIVE MEETINGS

INTEREST CATEGORIES ASSOCIATED WITH SAE BALLOT VOTING ARE:

- USERS - MEMBERS THAT UTILIZE ELECTRONIC EQUIPMENT TO PROVIDE SERVICES TO AN END USER.
- PRODUCERS - MEMBERS THAT SUPPLY ELECTRONIC EQUIPMENT.
- GENERAL INTEREST - MEMBERS ARE NEITHER PRODUCERS NOR USERS. THIS CATEGORY INCLUDES, BUT IS NOT LIMITED TO, GOVERNMENT, REGULATORY AGENCIES (STATE AND FEDERAL), RESEARCHERS, OTHER ORGANIZATIONS AND ASSOCIATIONS, AND/OR CONSUMERS.